

AUG 23 2002

**TRANSMITTAL LETTER
(General - Patent Pending)**

Docket No.
EN9-99-080

In Re Application Of: Caletka, et al.

Serial No.
09/438,037

Filing Date
11/10/1999

Examiner
Mitchell, J.

Group Art Unit
2827

Title: **PARTIALLY CAPTURED ORIENTED INTERCONNECTIONS FOR BGA PACKAGES AND A METHOD OF FORMING THE INTERCONNECTIONS**

TO THE COMMISSIONER OF PATENTS AND TRADEMARKS:

Transmitted herewith is:

Amendment (10 pages)
Postcard

RECEIVED
AUG 26 2002
TECHNOLOGY CENTER 2800

in the above identified application.

- ☒ No additional fee is required.
- ☐ A check in the amount of _____ is attached.
- ☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. **09-0457 (IBM)** as described below. A duplicate copy of this sheet is enclosed.
- ☐ Charge the amount of _____
- ☒ Credit any overpayment.
- ☒ Charge any additional fee required.

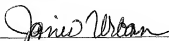

Signature

Dated: 8/20/2002

Arlen L. Olsen
Reg. No. 37,543
SCHMEISER, OLSEN & WATTS
3 Lear Jet Lane, Suite 201
Latham, NY 12110
(518) 220-1850

CC:

I certify that this document and fee is being deposited on 8/20/02 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Commissioner of Patents and Trademarks, Washington, D.C. 20231.


Signature of Person Mailing Correspondence

Janis Urban

Typed or Printed Name of Person Mailing Correspondence



Docket No.: EN9-99-080

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Caletka, et al.) Examiner: Mitchell, J.

Serial No.: 09/438,037) Art Unit: 2827

Filing Date: 11/10/99)

Title: PARTIALLY CAPTURED ORIENTED INTERCONNECTIONS FOR BGA
PACKAGES AND A METHOD OF FORMING THE INTERCONNECTIONS

Commissioner for Patents
Box AF
Washington D.C. 20231

RECEIVED
AUG 26 2002
TECHNOLOGY CENTER 2800

AF
2827

#11/B

Ans
N/E

J. McMillan
9/6/02

AMENDMENT under 37 C.F.R. §1.116(a)

Sir:

In response to the Office Action mailed June 20, 2002,
please amend the above-identified patent application as follows:

IN THE SPECIFICATION:

Please delete the paragraph beginning on page 7, line 14
through page 8, line 5, and insert the following:

--Fig. 3 shows the second surface 18 of the chip carrier 14
(refer to Fig. 1) covered with a mask 26. Similarly, Fig. 4
shows the first surface 24 of the board 20 covered with a mask
28. The masks 26, 28 have elongated non-circular, oblong, oval,
or elliptical openings 30 located over the conductive pads 16,
22. As illustrated in Fig. 5, the elongated openings 30 within

Serial No.: 09/438,037

1